FILE OROLIA ART_CARD

Réf PCB: ART CARD Rev 1	Réf PCB :	ART	CARD	Rev 1
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\vdash	7	SHEETS OF ELECTRICAL SCHEMATICS.
└ /	/	SHEETS OF FLECTRICAL SCHEMATICS

- □ ASSEMBLY DRAWING TOP
- ⇒ 1 ASSEMBLY DRAWING BOTTOM
- ⇒ 1 SILKSCREEN TOP
- ⇒ 1 SOLDER MASK TOP
- □ COPPER LAYER TOP
- □ COPPER LAYER INNER 1
- ⇒ 1 COPPER LAYER INNER 2
- ⇒ 1 COPPER LAYER INNER 3
- ⇒ 1 COPPER LAYER INNER 4
- ⇒ 1 COPPER LAYER BOTTOM
- ⇒ 1 SOLDER MASK BOTOM
- ⇒ 1 SILKSCREEN BOTTOM
- □ DRILL DRAWING
- ⇒ 1 STACK-UP

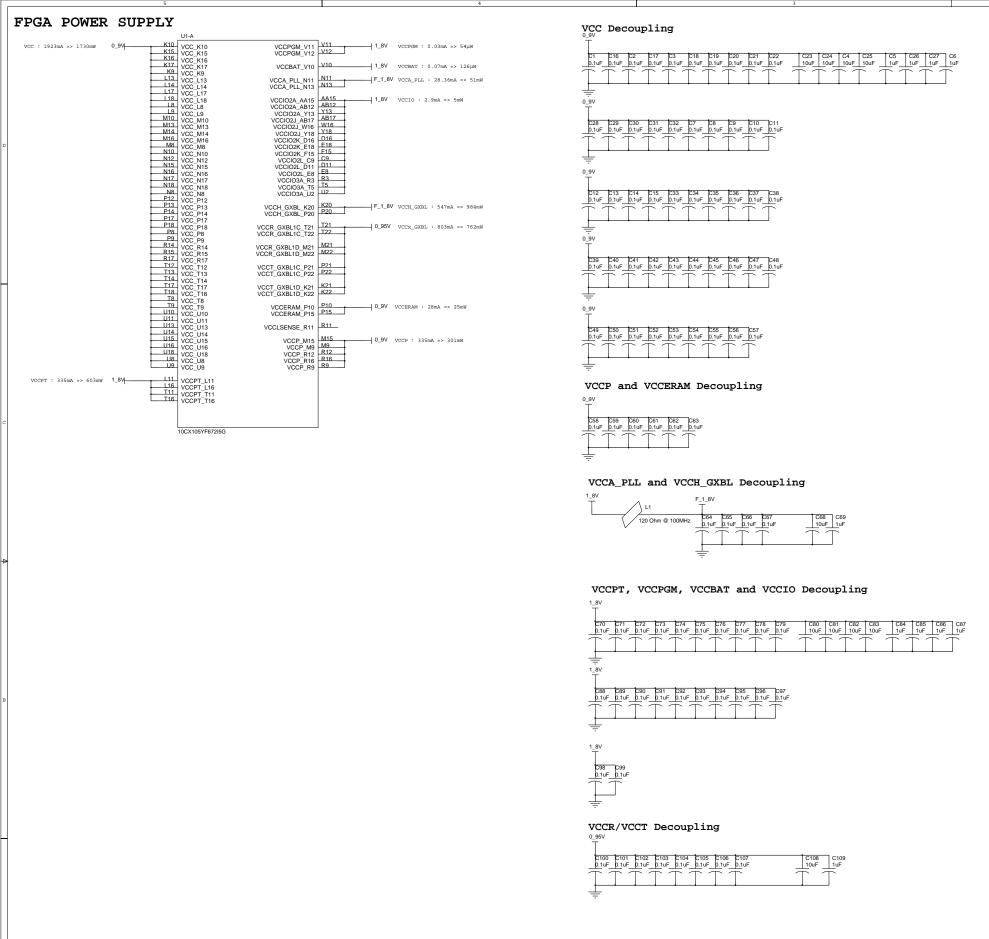


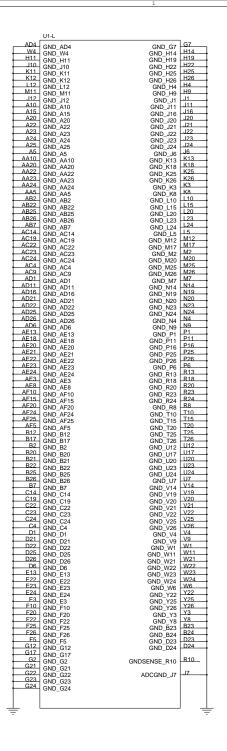
Tél.: +33(0)2-41-48-41-40 contact@artemis-cad.com

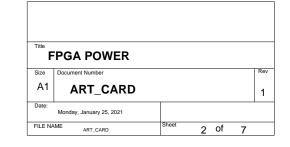
1 bis Avenue du Bois l'Abbé FRANCE

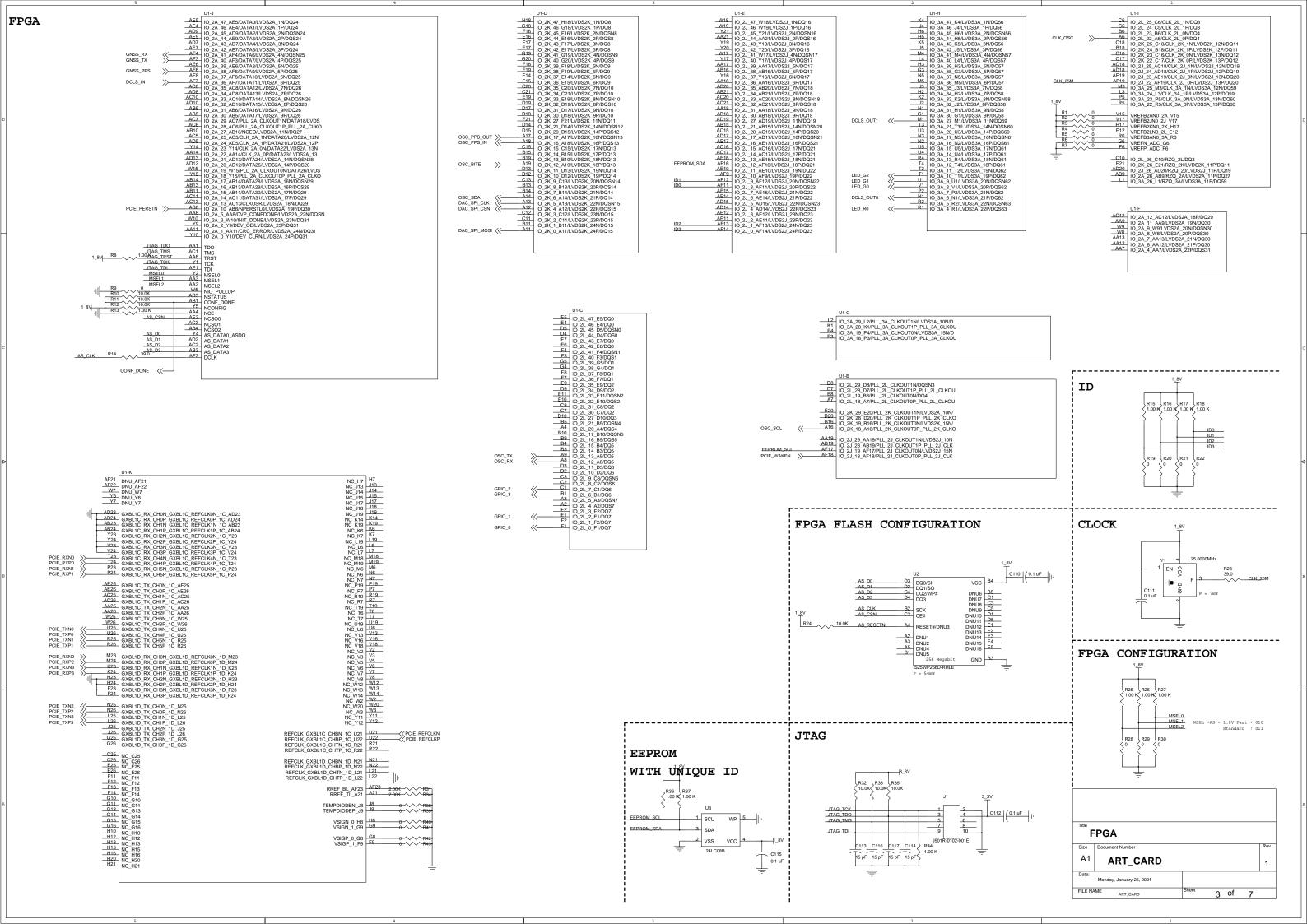
Fax: +33(0)2-41-48-41-44 www.artemis-cad.com

		,
4	2	Title









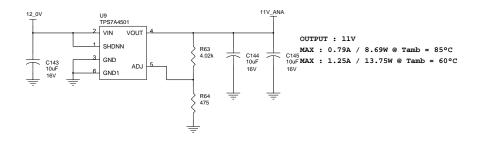
POWER NEED : FPGA : OCXO : Comp : TOTAL on 11V_ANA : : : 80 : 80 mW o5V.ovto: 3.3V LDO50 Consverter 12V to 5V Switch Converter On 3.3V On 1.8V : 243 : 243 mW 61 : 1704 mW On 0.95V : 762 : : 762 mW On 0.9V : 2056 : : 2056 mW -> 12695 mW TPS7A4501 10mV Ripple Voltage Max 2 VIN VOUT Output : 3.3V ___1_SHDNN R45 4.02k MAX : 0.46A / 1.53W @ Tamb = 85°C C120 10uF MAX : 0.73A / 2.42W @ Tamb = 60°C 16V 3 GND 6 GND1 C122 22uF 16V C124 47uF 6.3V C125 47uF 6.3V R47 73.2 K R48 MODE/SYNC INTVCC 2 VC 22 R50 10.0K C126 2200 pF CLKOUT 19 POWERGOOD 23 R53 10.0K 5_0V PGOOD_5V0_ 5V to 1.8V Switch Converter 9 MODE/SYNC 4 PGND PGOOD - PGND PGND PGND(PAD) AGND -PGOOD_1V8_ 5V to 0.95V Switch Converter R57 90.9K C136 R58 47uF > 100 K 6.3V 4 PGND PGOOD 11 PGND PGND PGND AGND 1 1 TC3308A PGOOD_0V95 5V to 0.9V Switch Converter R60 80.6 k

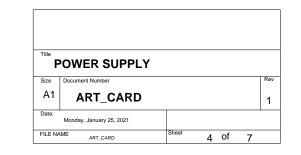
2 EN 9 MODE/SYNC

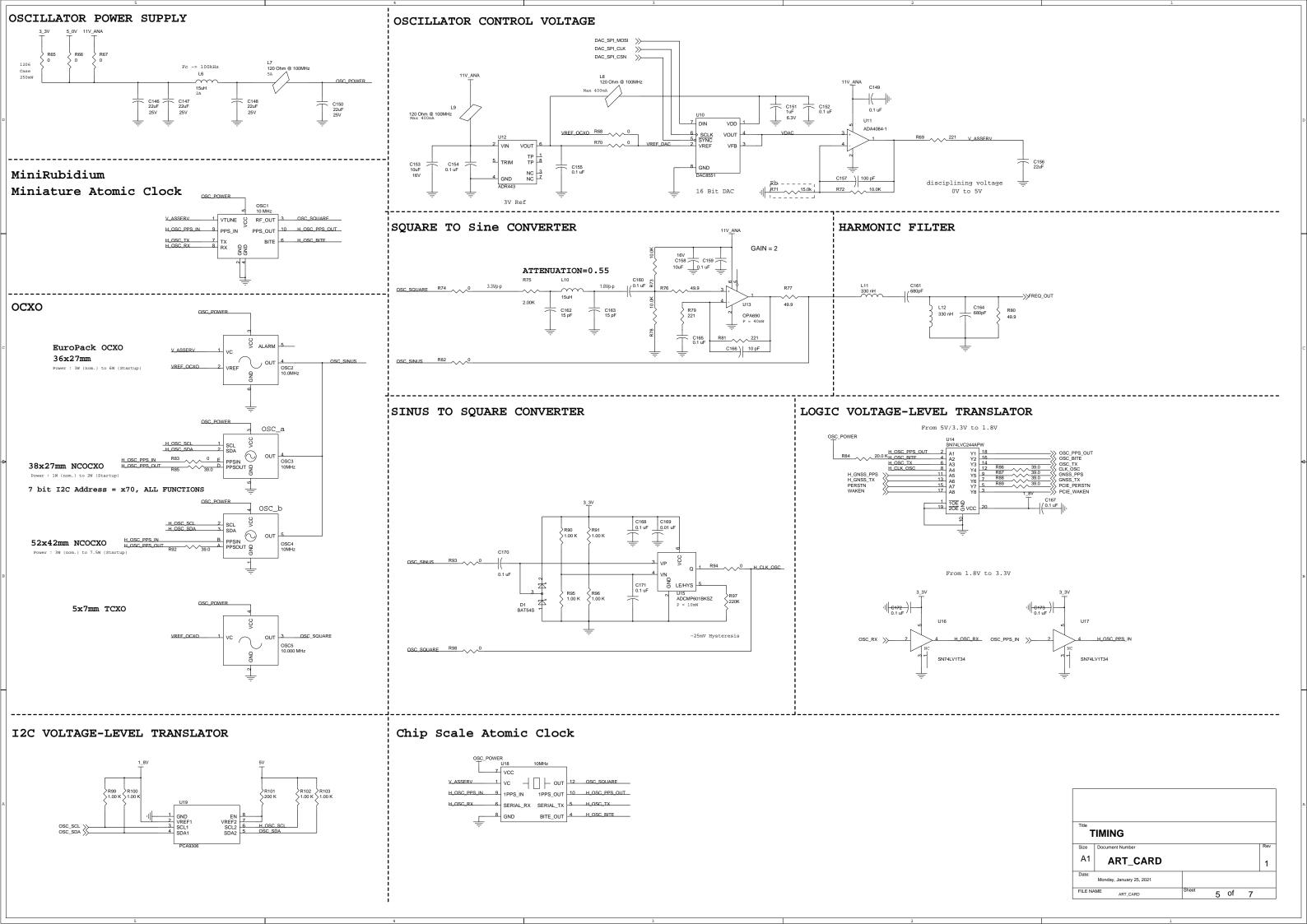
4 PGND PGOOD 11.
7 PGND PGND AGND 1

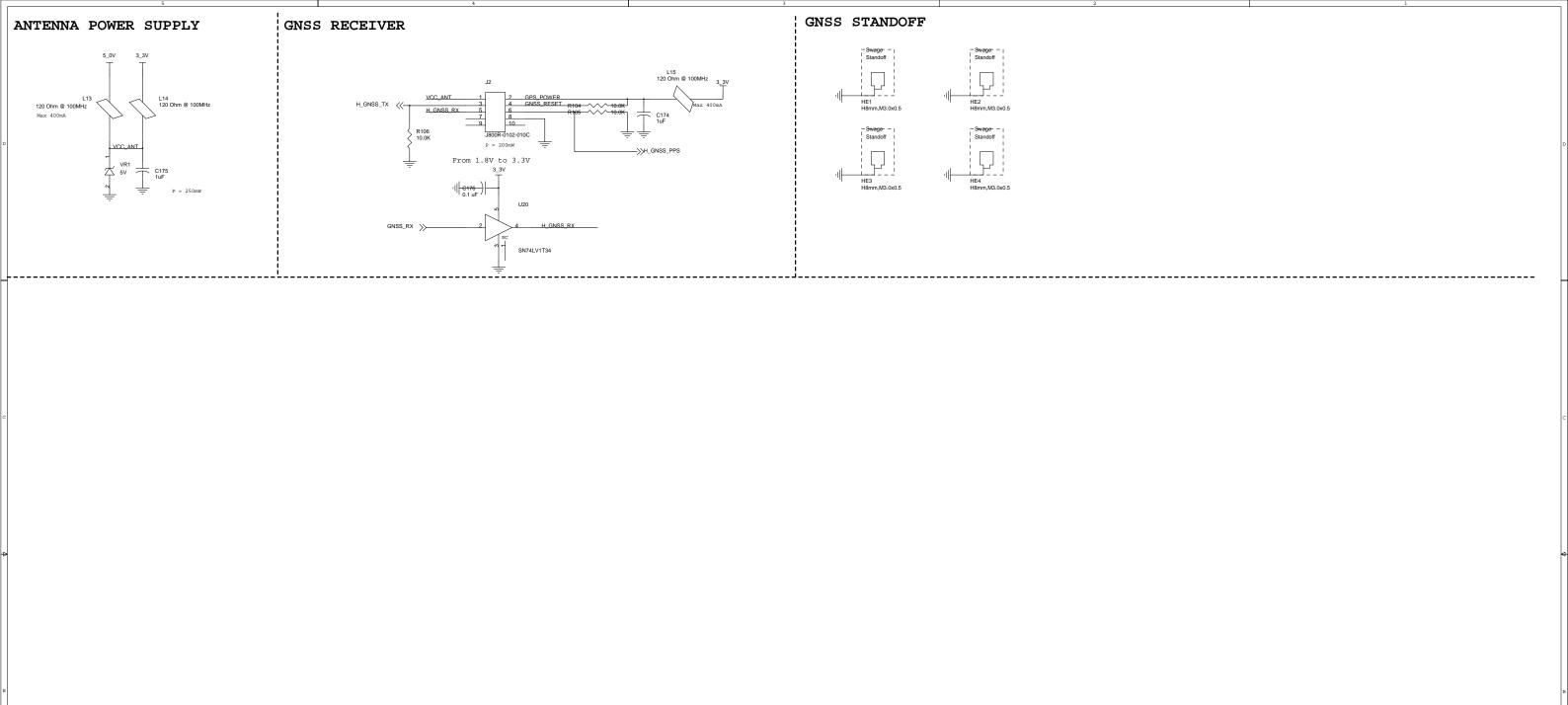
PGOOD_0V9

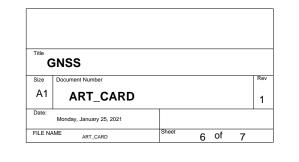
ANALOG POWER SUPPLY

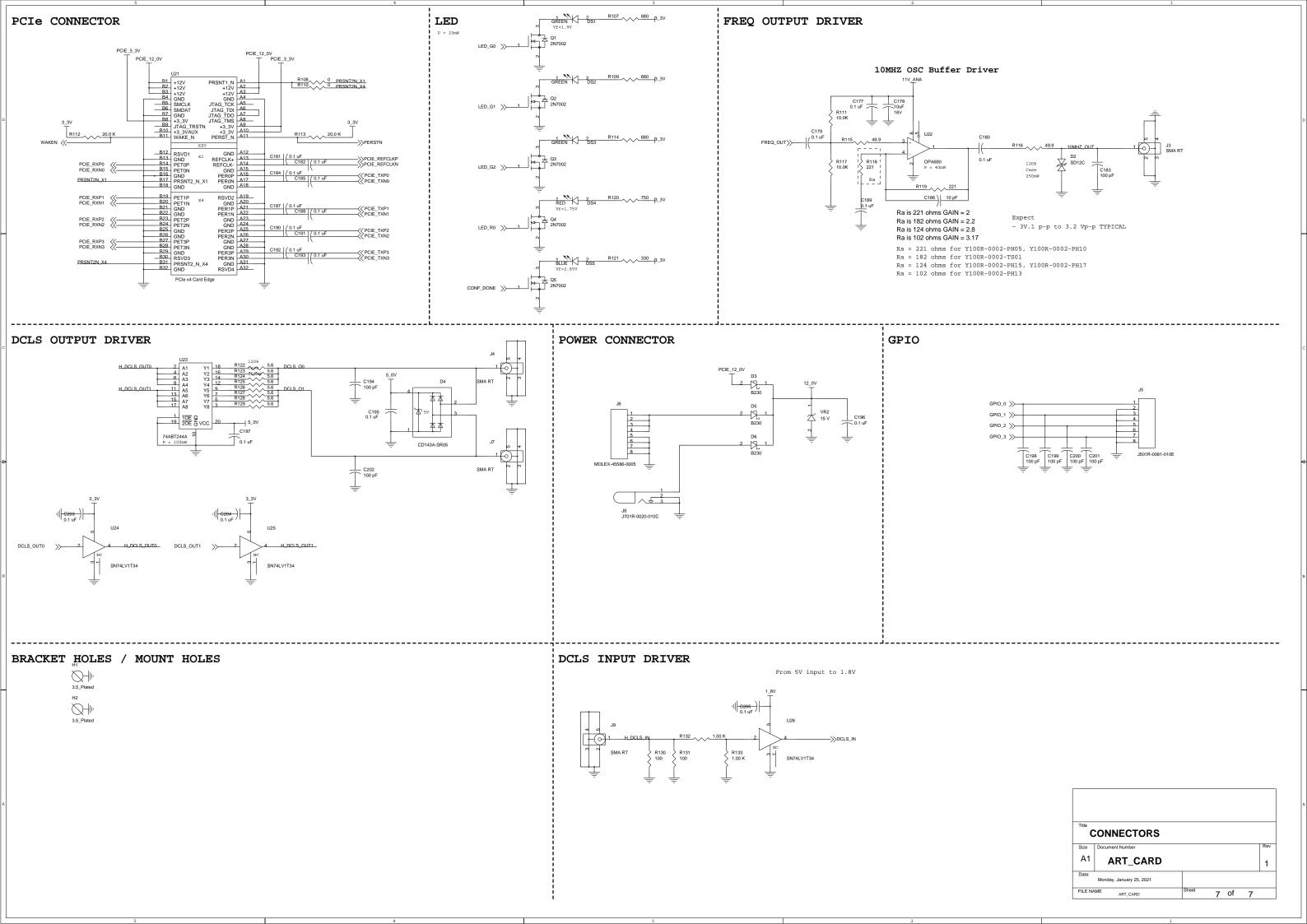


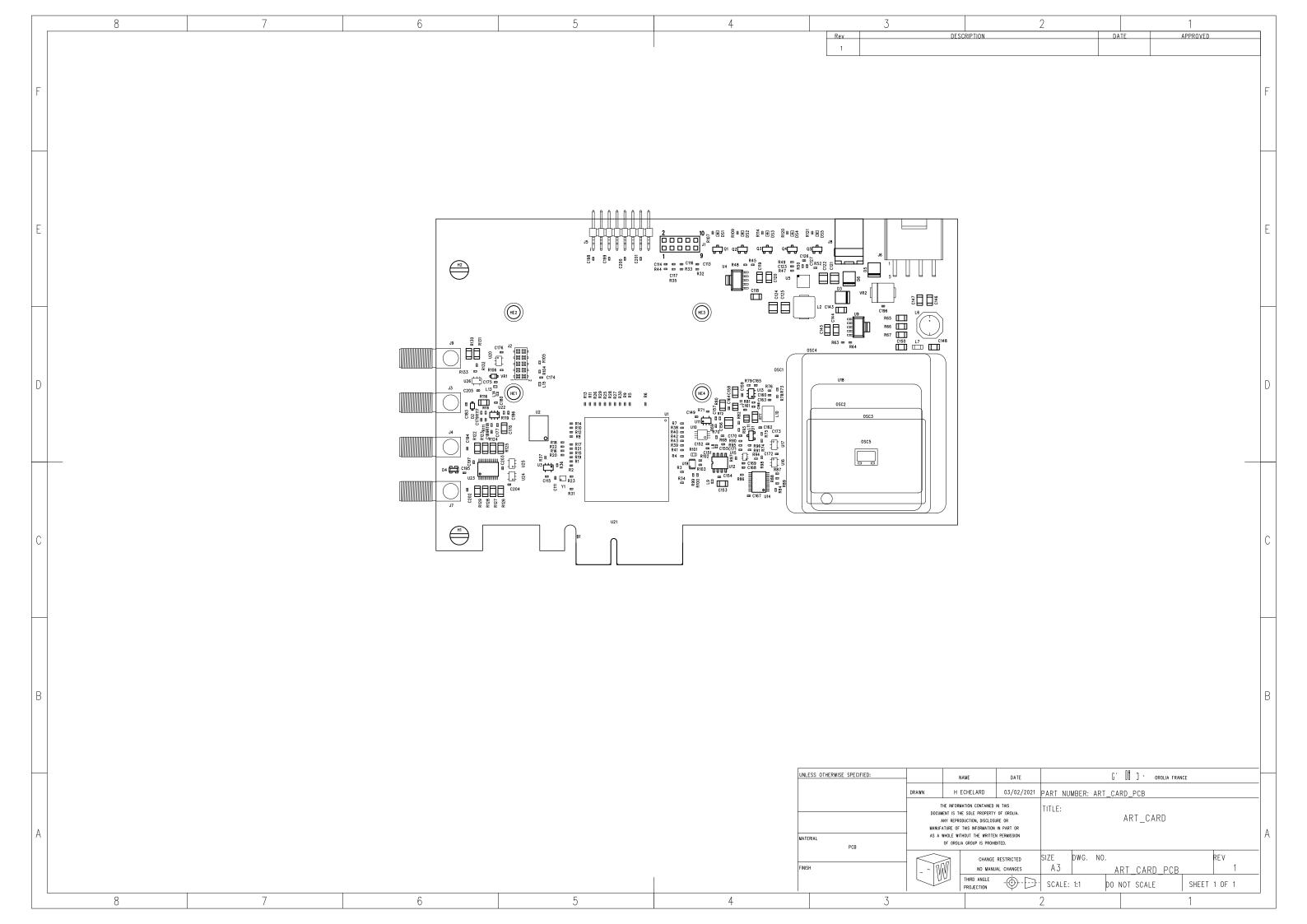


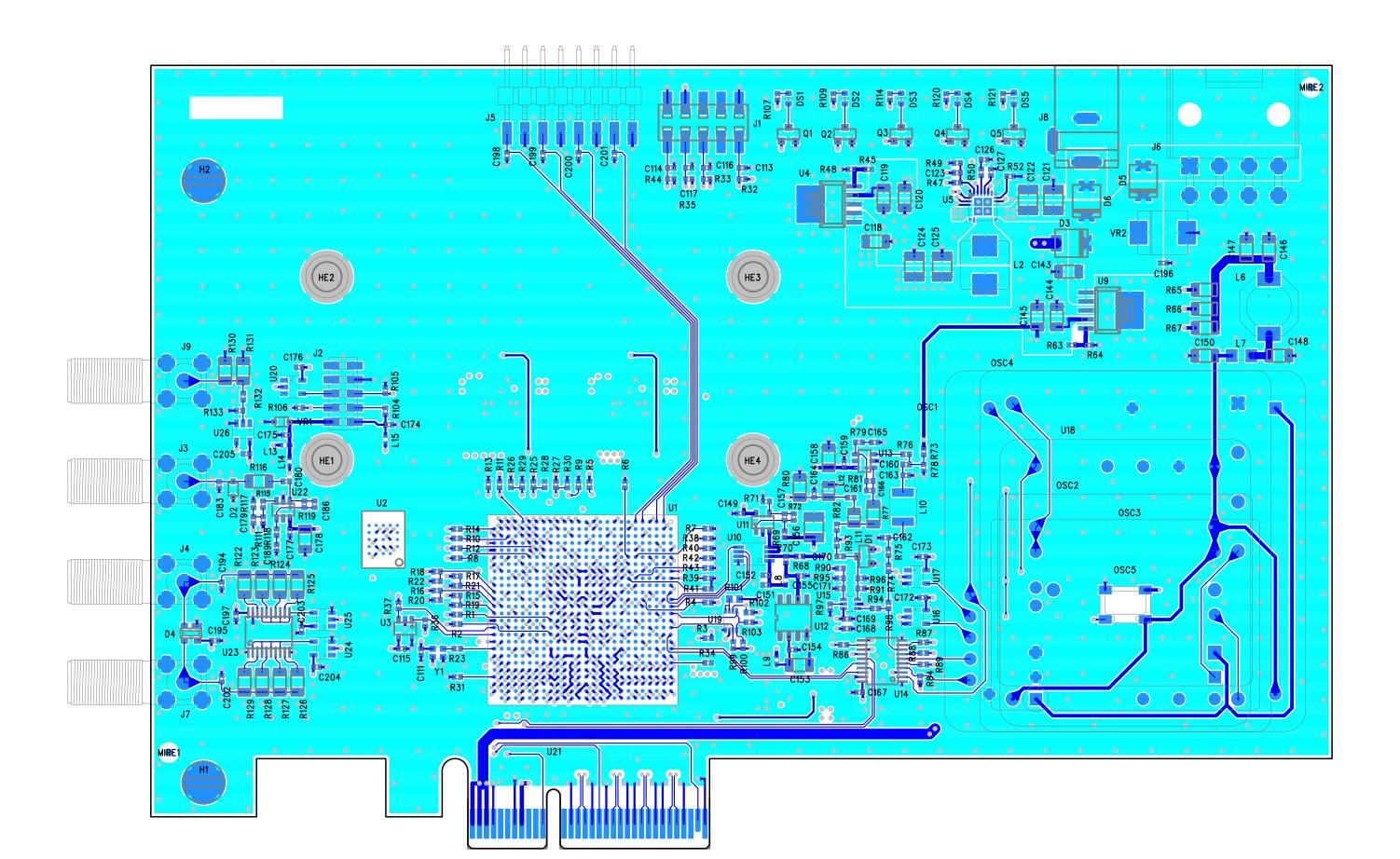


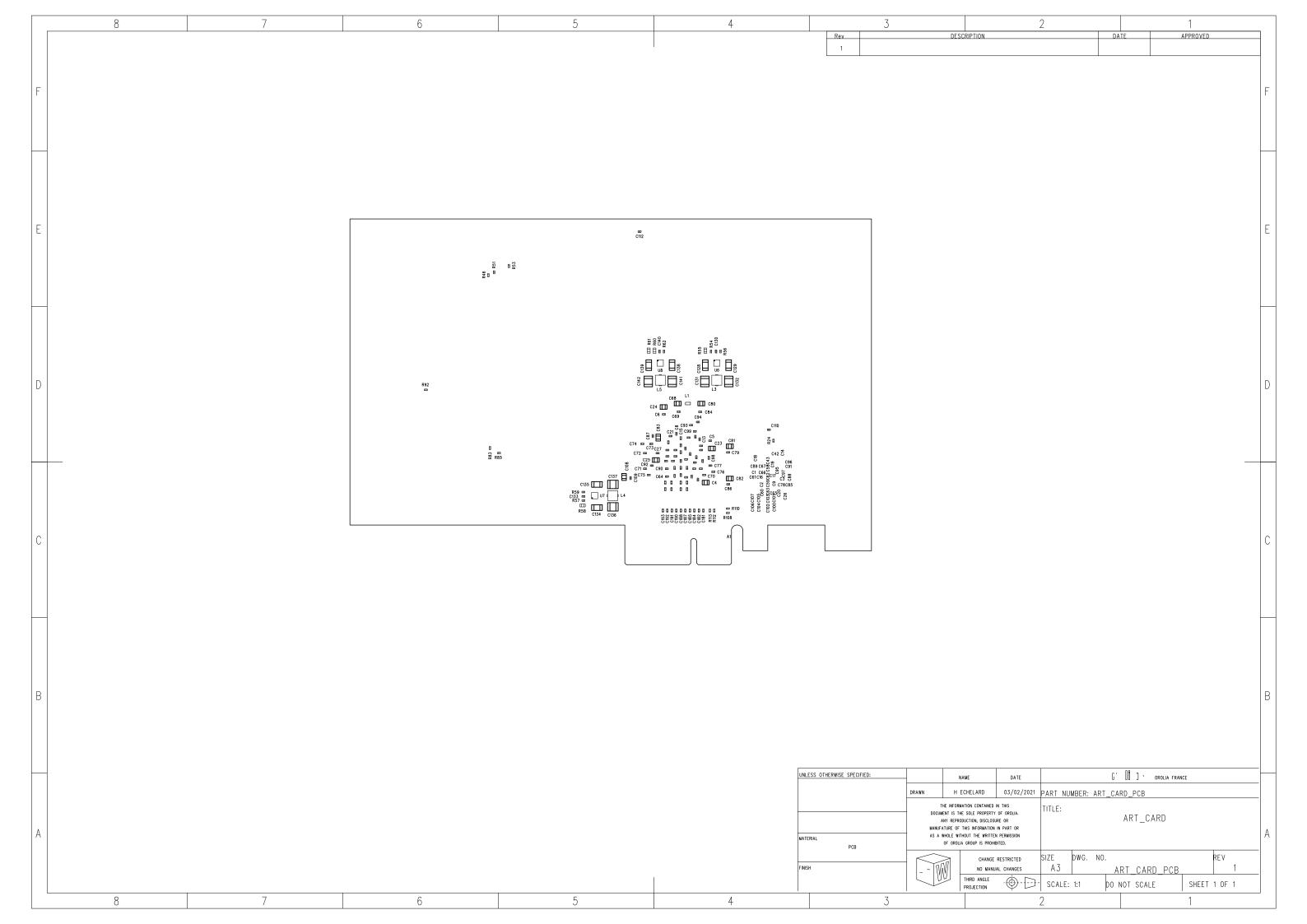


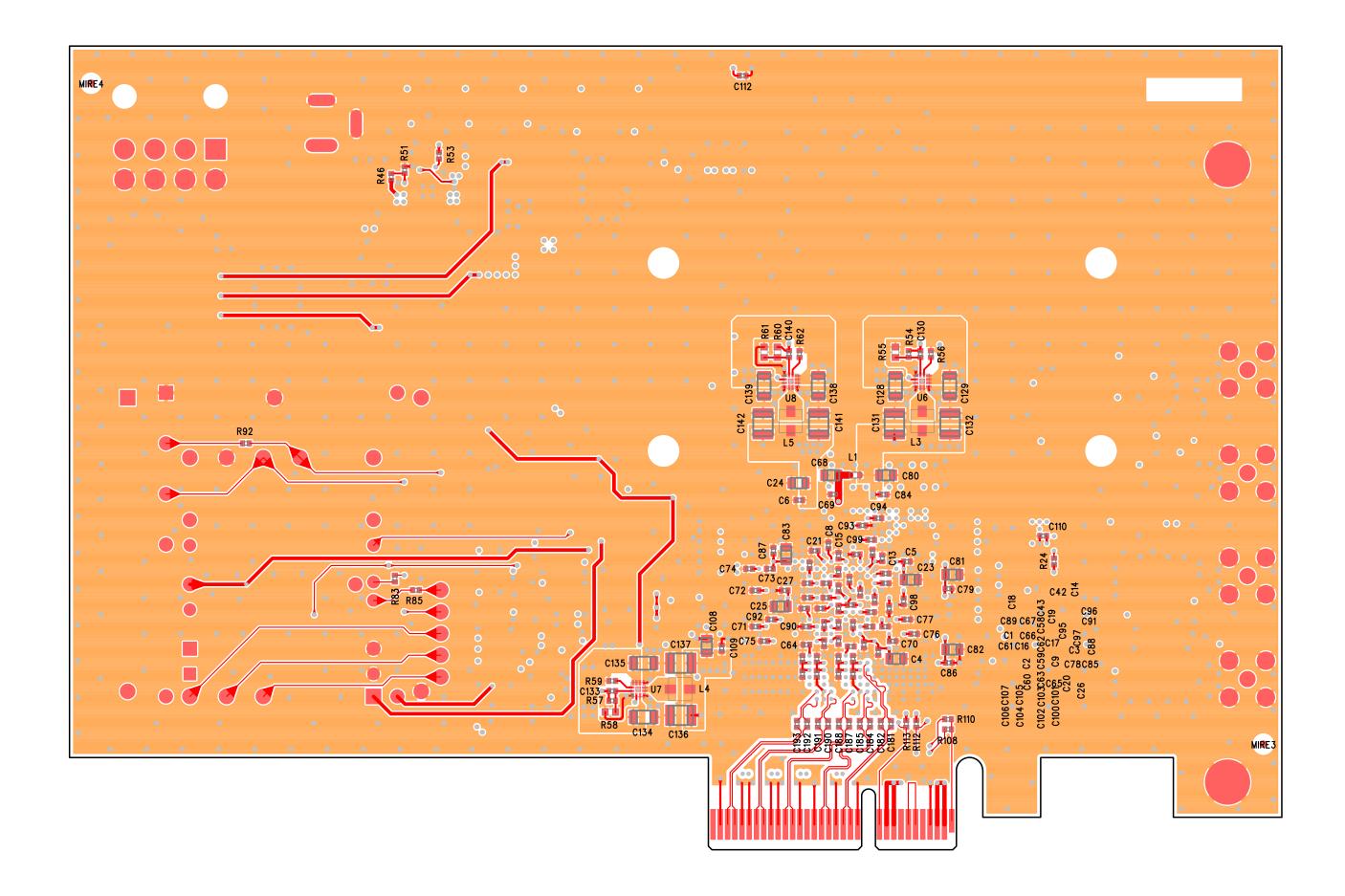






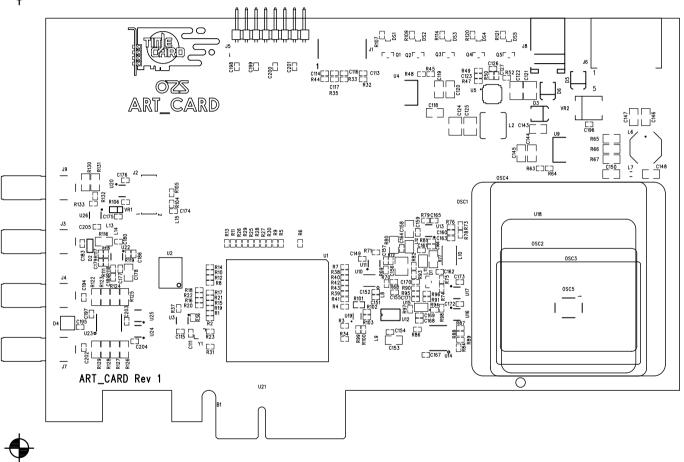










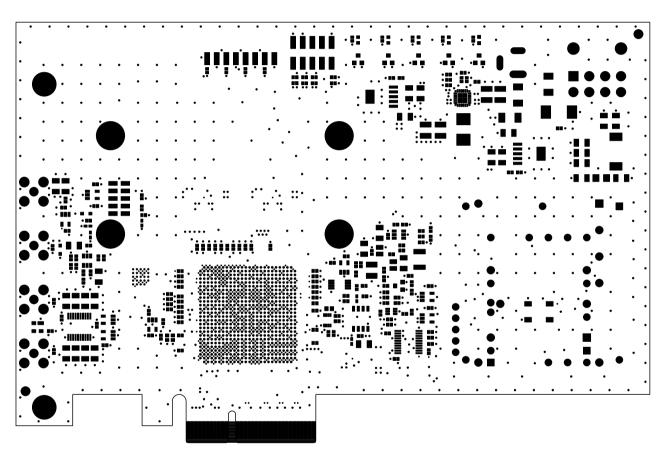




SILKSCREEN TOP	ARTEMIS
FILE: ART_CARD REV 1	02/04/21





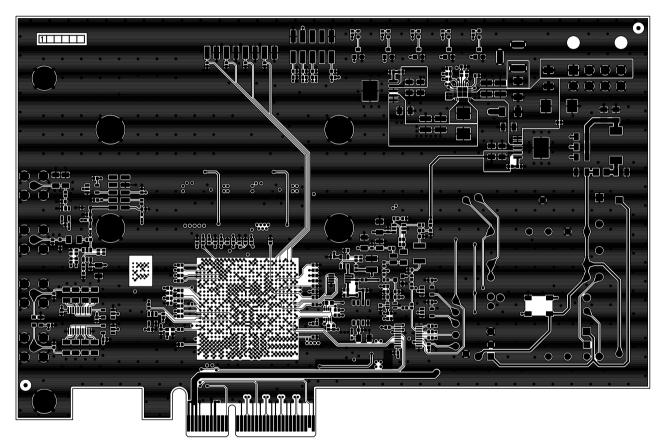




	SOLDER	MASK	TOP	ARTEMIS
ILE:	ART	CARD	REV 1	02/04/21





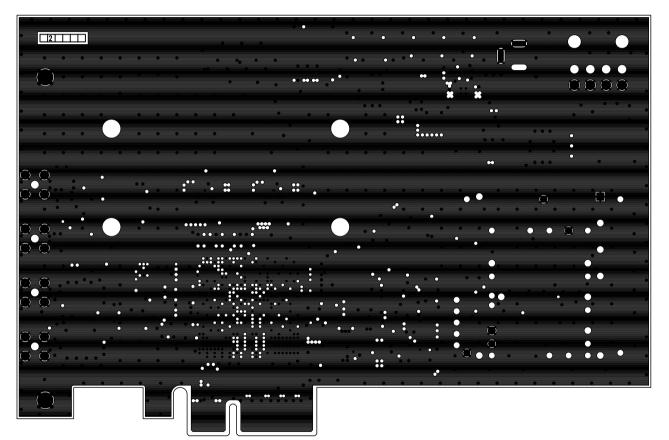




	TOP LAYER	ARTEMIS
FILE:	ART_CARD REV 1	02/04/21





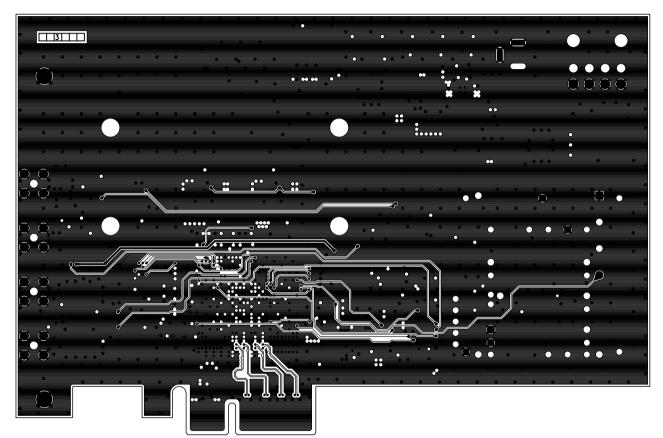




	INTERNAL 1 LAYER	ARTEMIS
FILE:	ART_CARD REV 1	02/04/21





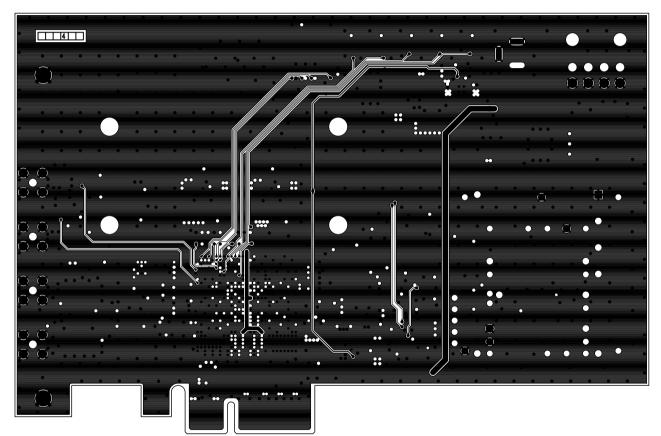




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FILE:	ART_CARD REV 1	02/04/21





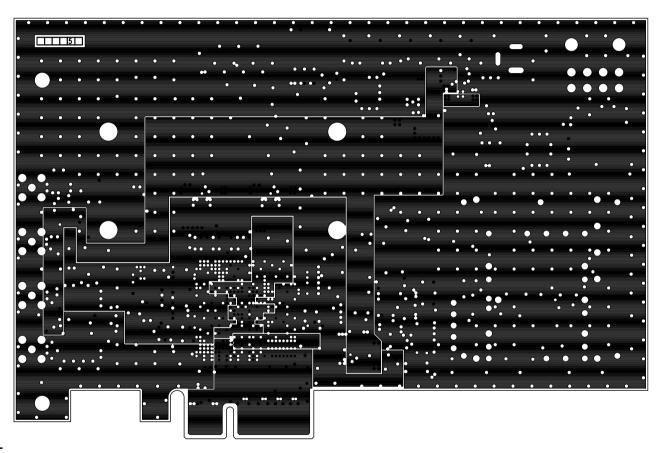




	INTERNAL 3 LAYER	ARTEMIS
FILE:	ART CARD REV 1	02/04/21





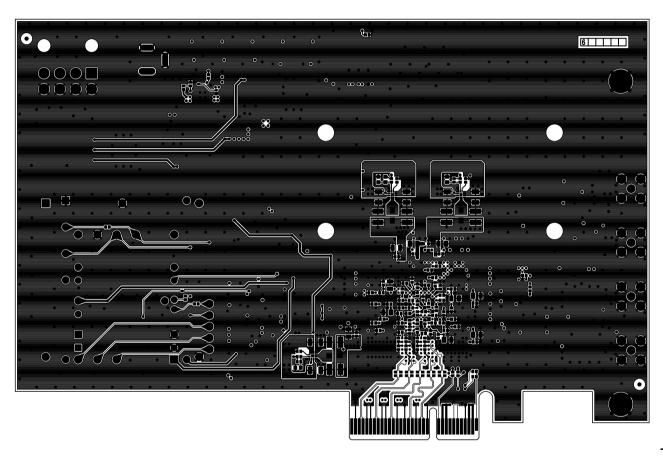




FILM:	COUCHE	INTERNE 4	ARTEMIS
FILE:	ART_	_CARD_REV_1	02/04/21



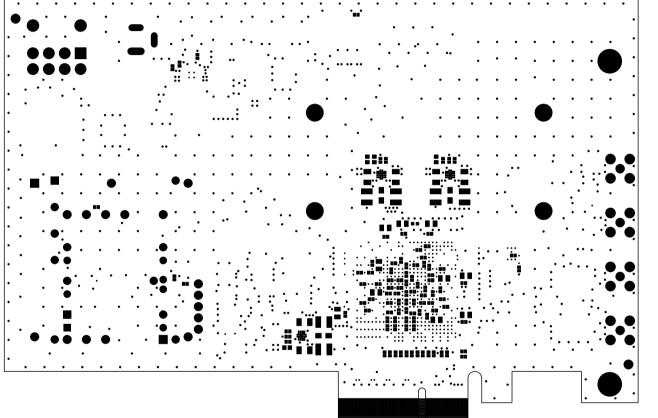




	BOTTOM LAYER	ARTEMIS
FILE:	ART_CARD REV 1	02/04/21







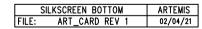
	SOLDER MASK BOTTOM	ARTEMIS
FILE:	ART_CARD REV 1	02/04/21



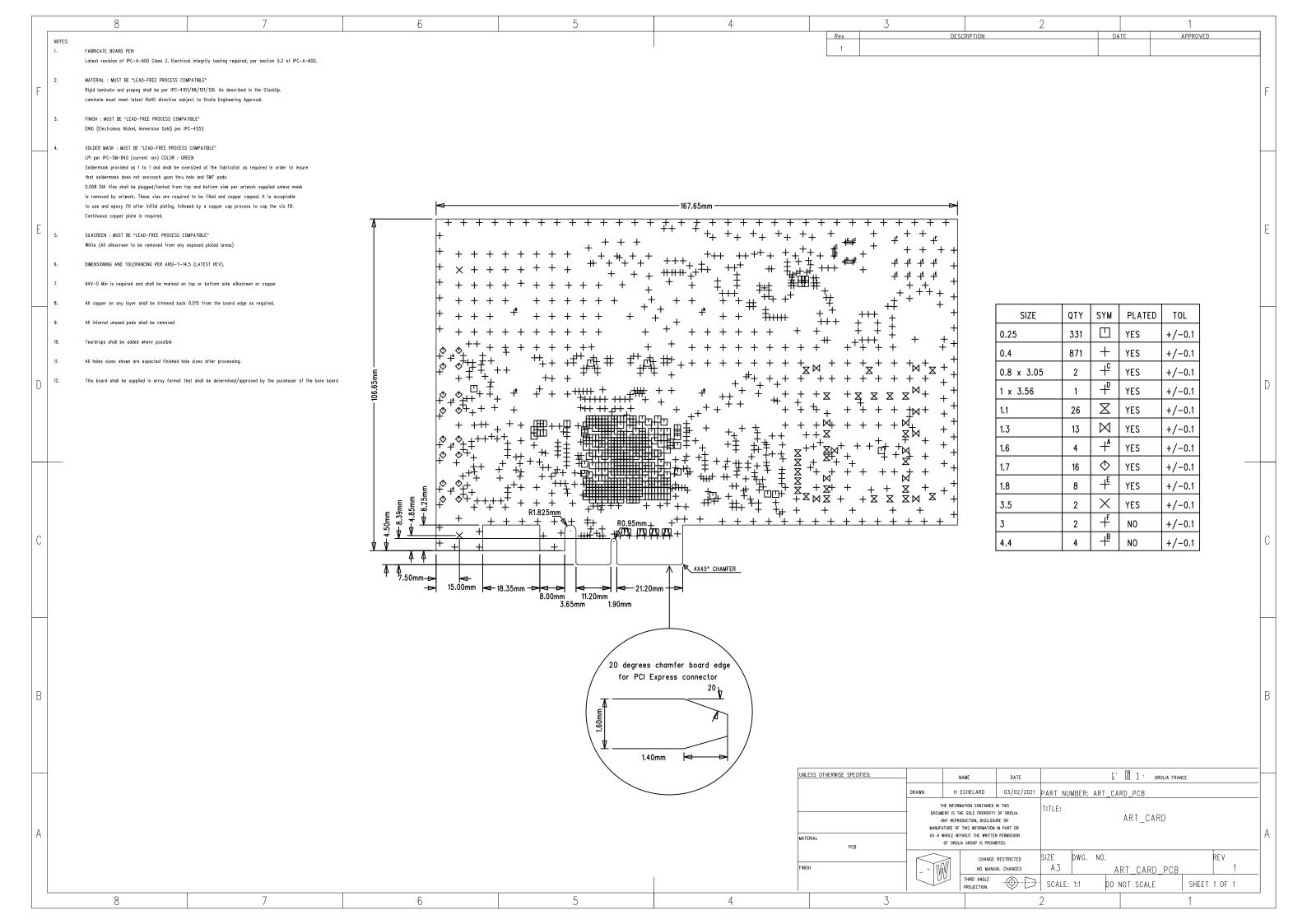




		CII2
	R46 C 1 R51 C 1 R53	
R92 C I	□ See Mag See	224









Layer	Stack up	Supplier	Description	Supplier Description	Туре	Base Thickness	Finish Thickness	Mask Thickness	εr	Loss Tangent	Resin Content	Impedance ID
			Solder resist	LPI	Solder resist			0.020	4.100	0.0000		
1			Foil	17um Copper Foil	Foil	0.018	0.040					1, 2
		VENTEC	VT47-2113	VT-47	PREPREG	0.106	0.095		4.060	0.0000	57.000	
2						0.017	0.017					
3		VENTEC	VT-47	0.127mm	Core	0.127 0.017	0.127 0.017		4.350	0.0000	0.000	3,4
		VENTEC	VT47-2116	VT-47	PREPREG	0.132	0.121		4.150	0.0000	54.000	0, 4
(VENTEC		0.711mm	Core	0.711	0.711			0.0000	0.000	
Ġ			VT47-2116	VT-47	PREPREG	0.132	0.121			0.0000	54.000	
1		VEIVIEC	V147-2110	V1-47	THETHEG	0.017	0.017		4.150	0.0000		5, 6
· ,		VENTEC	VT-47	0.127mm	Core	0.127	0.127		4.350	0.0000	0.000	5, 0
5						0.017	0.017					
		VENTEC	VT47-2113	VT-47	PREPREG	0.106	0.095		4.060	0.0000	57.000	
6	+1		Foil	17um Copper Foil	Foil	0.018	0.040					7, 8
			Solder resist	LPI	Solder resist			0.020	4.100	0.0000		

Copper Thickness = 0.148 | Dielectric Thickness = 1.399 | Solder Mask Thickness = 0.040 | Stack Up Thickness = 1.546 | Stack Up Thickness with Soldermask = 1.586

Impedance ID	Structure Image	Structure Name	Impedance Signal Layer	Ref. Plane 2 in Layer	Ref. Plane 1 in Layer	Lower Trace Width (W1)	Trace Separation (S1)	Ground Strip Separation (D1)	Broadside 2nd Layer	Calculated Impedance	Target Impedance	Tol (+/- %)	Coating Between Traces (C3)
		Coated Microstrip 1B	1	0	2	0.150	0.000	0.000	0	50.090	50.000	10.000	0.000
2		Edge Coupled Coated Microstrip 1B	1	0	2	0.150	0.150	0.000	0	87.470	85.000	10.000	0.020
3		Offset Stripline 1B1A	3	5	2	0.160	0.000	0.000	0	50.950	50.000	10.000	0.000
4	-00	Edge Coupled Offset Stripline 1B1A	3	5	2	0.160	0.150	0.000	0	85.010	85.000	10.000	0.000
5		Offset Stripline 1B1A	4	5	2	0.160	0.000	0.000	0	50.950	50.000	10.000	0.000
6		Edge Coupled Offset Stripline 1B1A	4	5	2	0.160	0.150	0.000	0	85.010	85.000	10.000	0.000
7		Coated Microstrip 1B	6	0	5	0.150	0.000	0.000	0	50.090	50.000	10.000	0.000

StackName: Ouestronic_PCl Express_246183-Q_6L_VT47	Version:	Revision:	Modification:	Date of Revision:	Editor	
Date: 28/01/2021	Associated Documents:					
Author: Mostefa Abdali						Page 1/2
Department: IDS						
Site: Tewkesbury						



Impedance ID	Structure Image	Structure Name	Impedance Signal Layer	Plane 2	Ref. Plane 1 in Layer	Lower Trace Width (W1)		Ground Strip Separation (D1)	Broadside 2nd Layer	Calculated Impedance	Target Impedance	Tol (+/- %)	Coating Between Traces (C3)	
8	andanan	Edge Coupled Coated Microstrip 1B	6	0	5	0.150	0.150	0.000	0	87.470	85.000	10.000	0.020	

Drill Image	1st Layer	2nd Layer	Drill Type	Minimum Size	Fill Type	Data Filenames	Minimun Pad Size
·	1	6	Mechanical PTH	0.250	None		0.500

<u>Notes</u>

StackName: Ouestronic_PCl Express_246183-Q_6L_VT47	Version:	Revision:	Modification:	Date of Revision:	Editor		
Date: 28/01/2021	Associated Documents:						
Author: Mostefa Abdali						Page 2/2	
Department: IDS							
Site: Tewkesbury							



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www.artemis-cad.com

TECHNICAL SPECIFICATION

IPC-A-600

CUSTUMER: OROLIA

MANUFACTURER:

PCB Reference :	ART_CARD	Index: Rev 1
✓ PCB Unit	Unit PCB dimensions :	167.65 X 106.65 mm
Panel PCB: 0	Panel dimensions :	0 X 0 mm
Material: FR4	Surface :	1.79 dm ² Track / Gap: 0.15 / 0.15 mm
PCB Type :	MC6 Finis	ch Copper Thikness (μm) : 12μ 17,5μ 35μ 40μm
PCB Thickness (mm):	16/10	External Layer :
	<u></u>	Intern Layer :
Technology ✓	Plated Trough Hole	Via type: Hole / pads ratio: 0,25/0,55
✓ Traditional	Press-fit Hole	Traditional Via Via in pad
√ SMT	Autre	Laser Via Stacked Staggered
Surface Treatement Finished	1	Blinded Via Couche départ et d'arrivée
✓ Ni/Au Chemical	Sn/Pb surfondu	Buried Via Couche départ et d'arrivée
Sn/Cu HAL	Autre	Filled Via Resin Copper
Peelable Solder Mask	Standard	ТОР ВОТТОМ
Solder Mask	Photo-imageable	Green ✓ TOP ✓ BOTTOM
Silkscreen ✓	Ink	White ✓ TOP ✓ BOTTOM
Electrical Test		✓ Yes No
Impedance control :		✓ Produced Measured
50 ohms on layer 1, 3 and 4		
✓ Differential Pairs :		✓ Produced Measured
85 ohms on layer 1, 3 and 6		
✓ Stack-up :	Ouestronic_PCI Expre	ss_246183-Q_6L_VT47.pdf
Milling	Milling Diameter :	0 mm
Comments :		